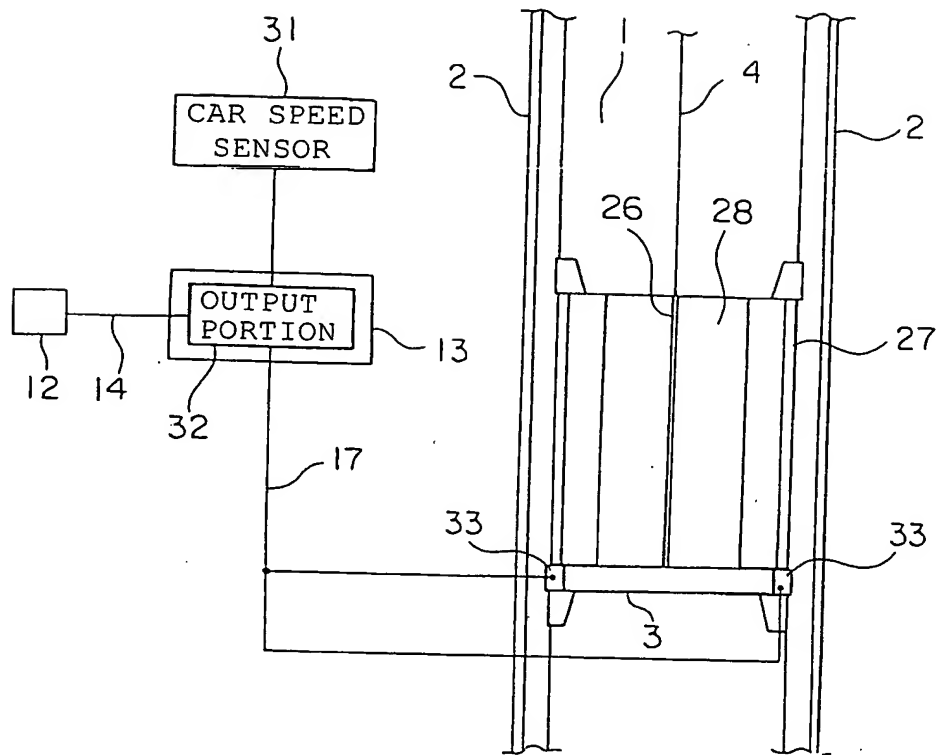


FIG. 1



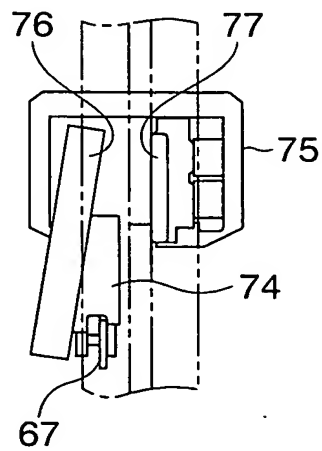


FIG. 4

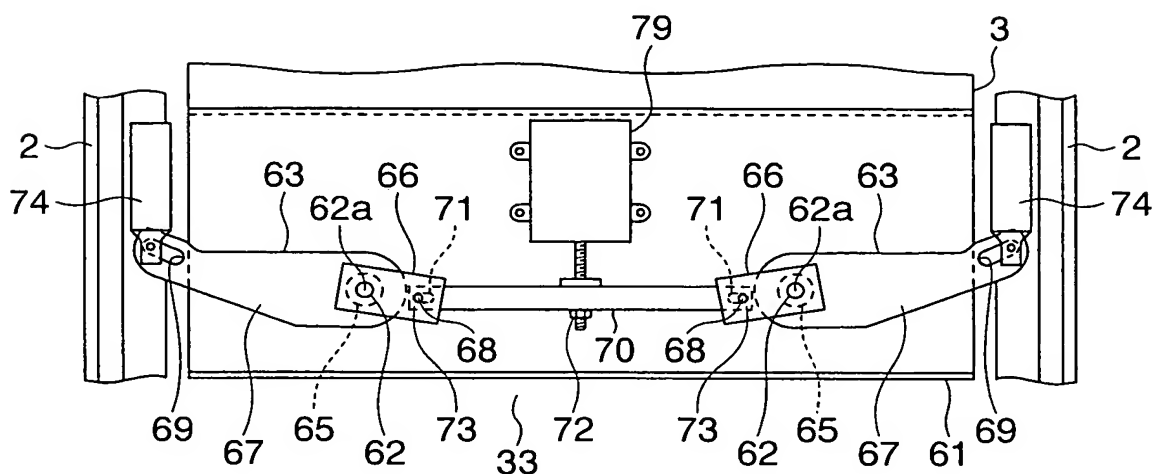


FIG. 5

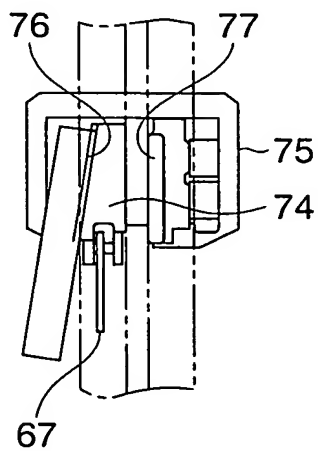


FIG. 6

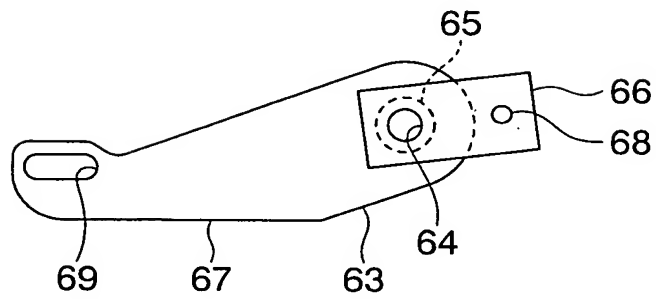


FIG. 7

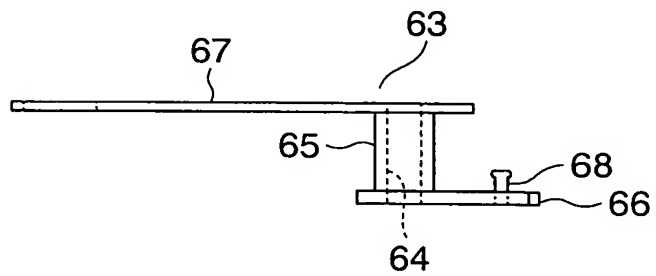


FIG. 8

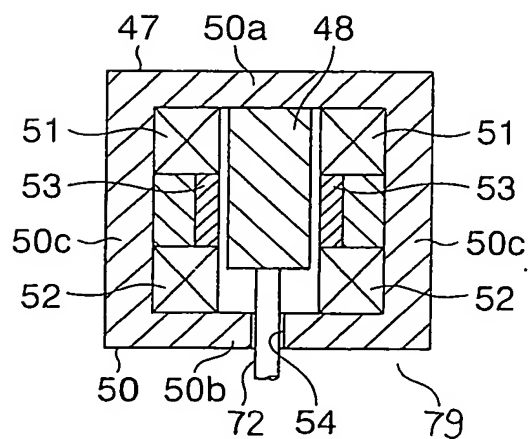


FIG. 9

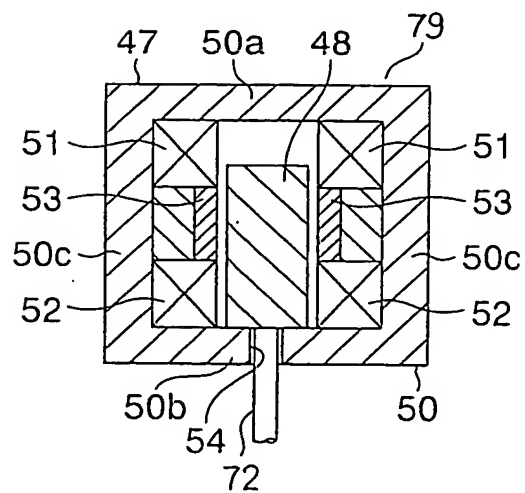


FIG. 10

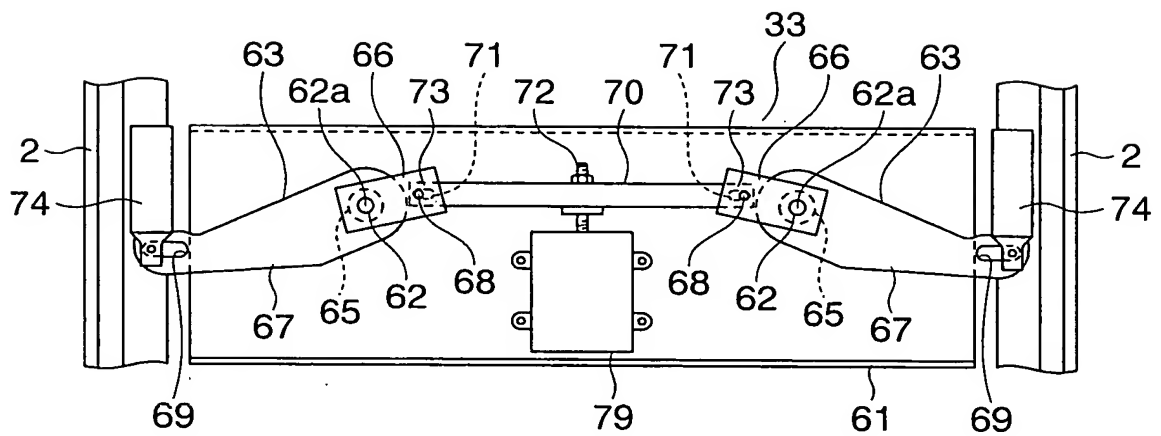


FIG. 11

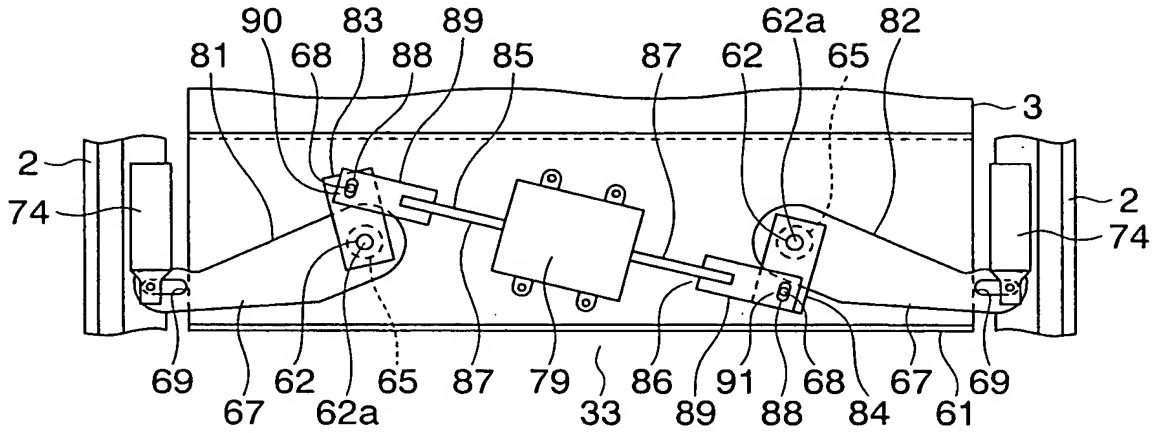


FIG. 12

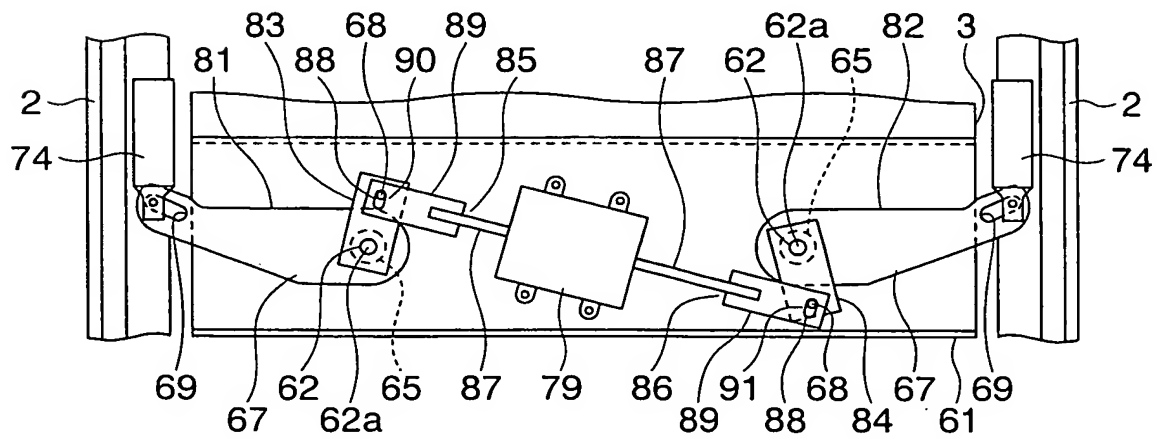


FIG. 13

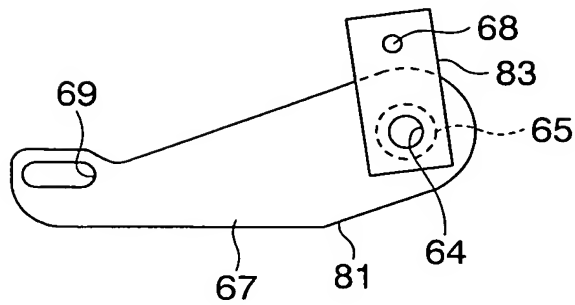


FIG. 14

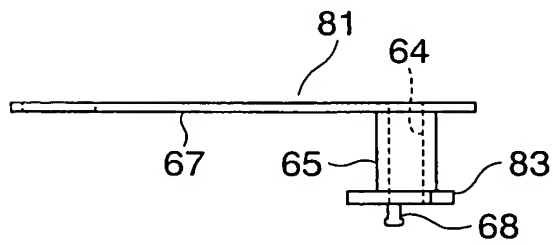


FIG. 15

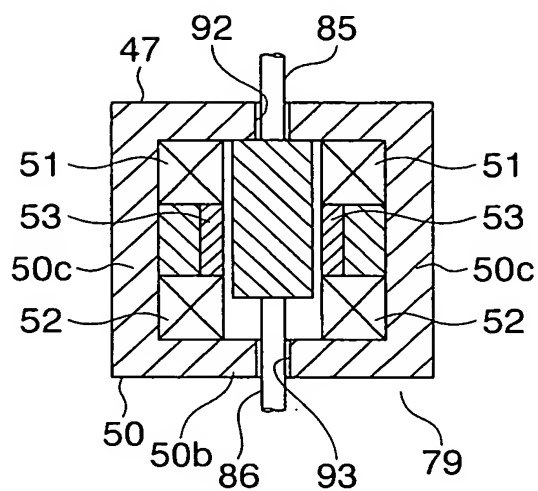


FIG. 16

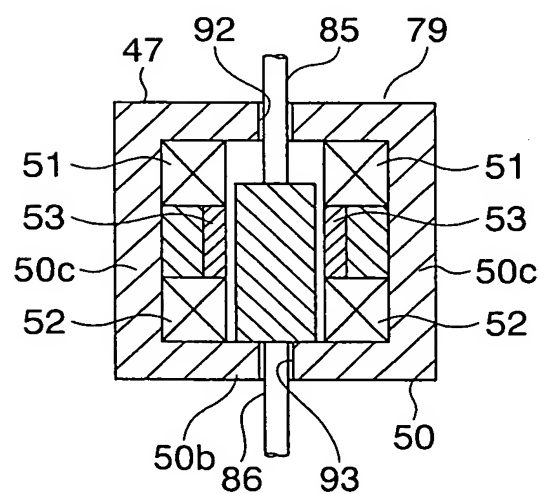


FIG. 17

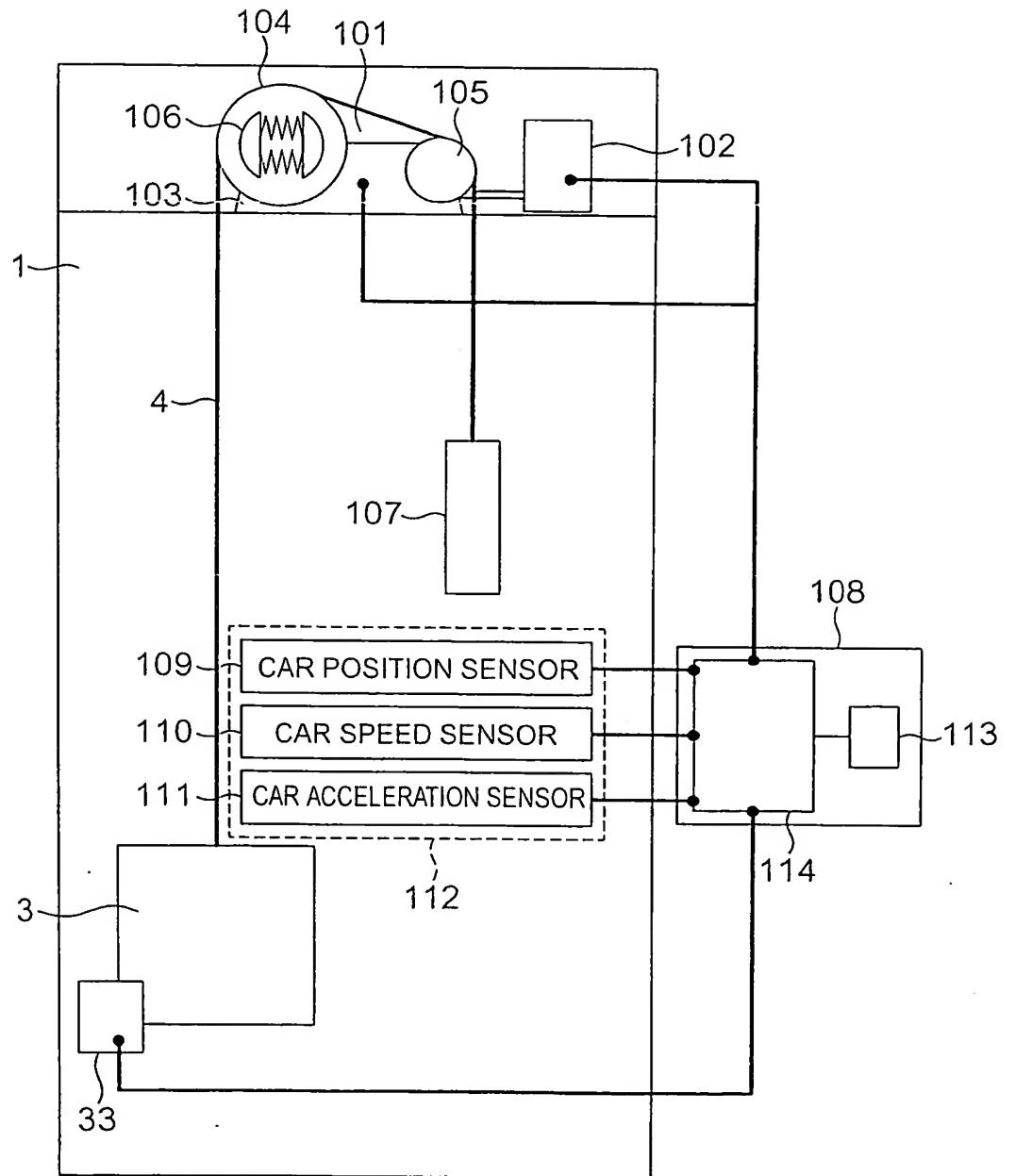


FIG. 18

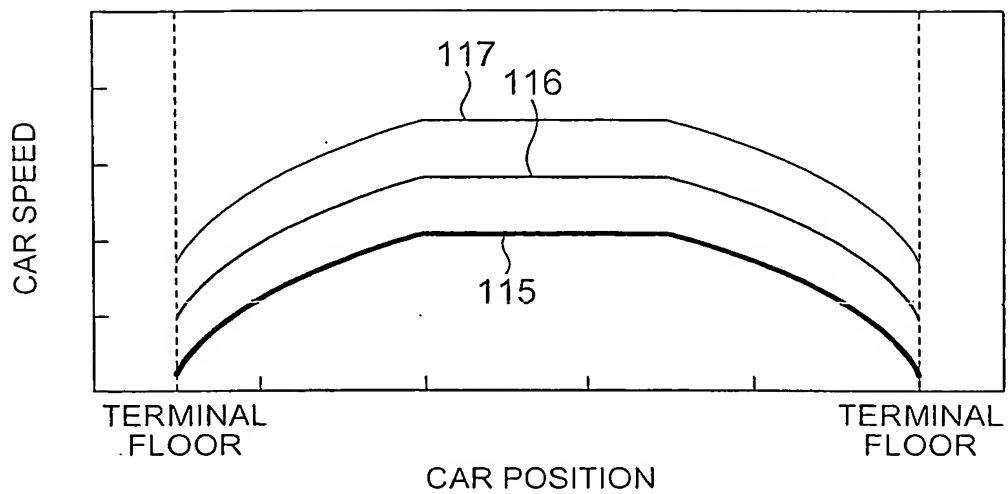


FIG. 19

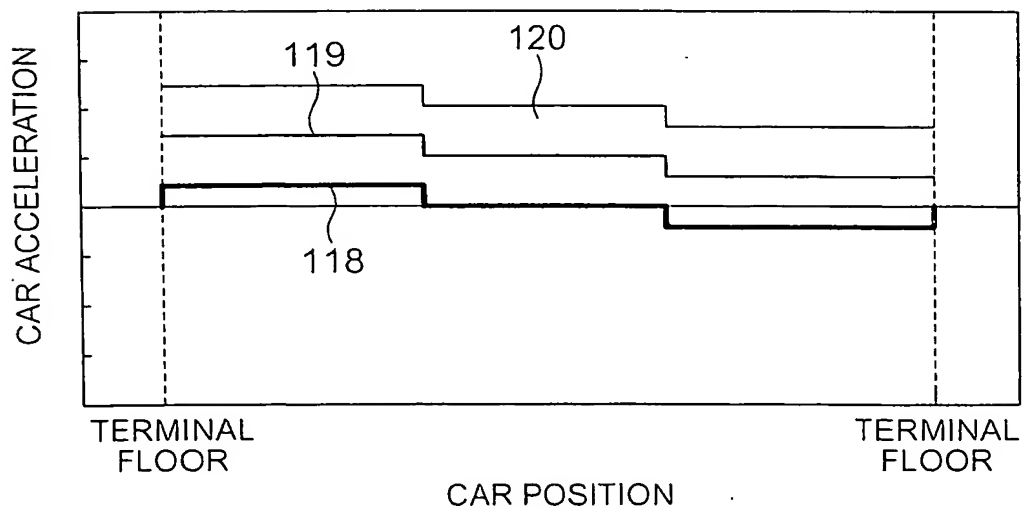


FIG. 20

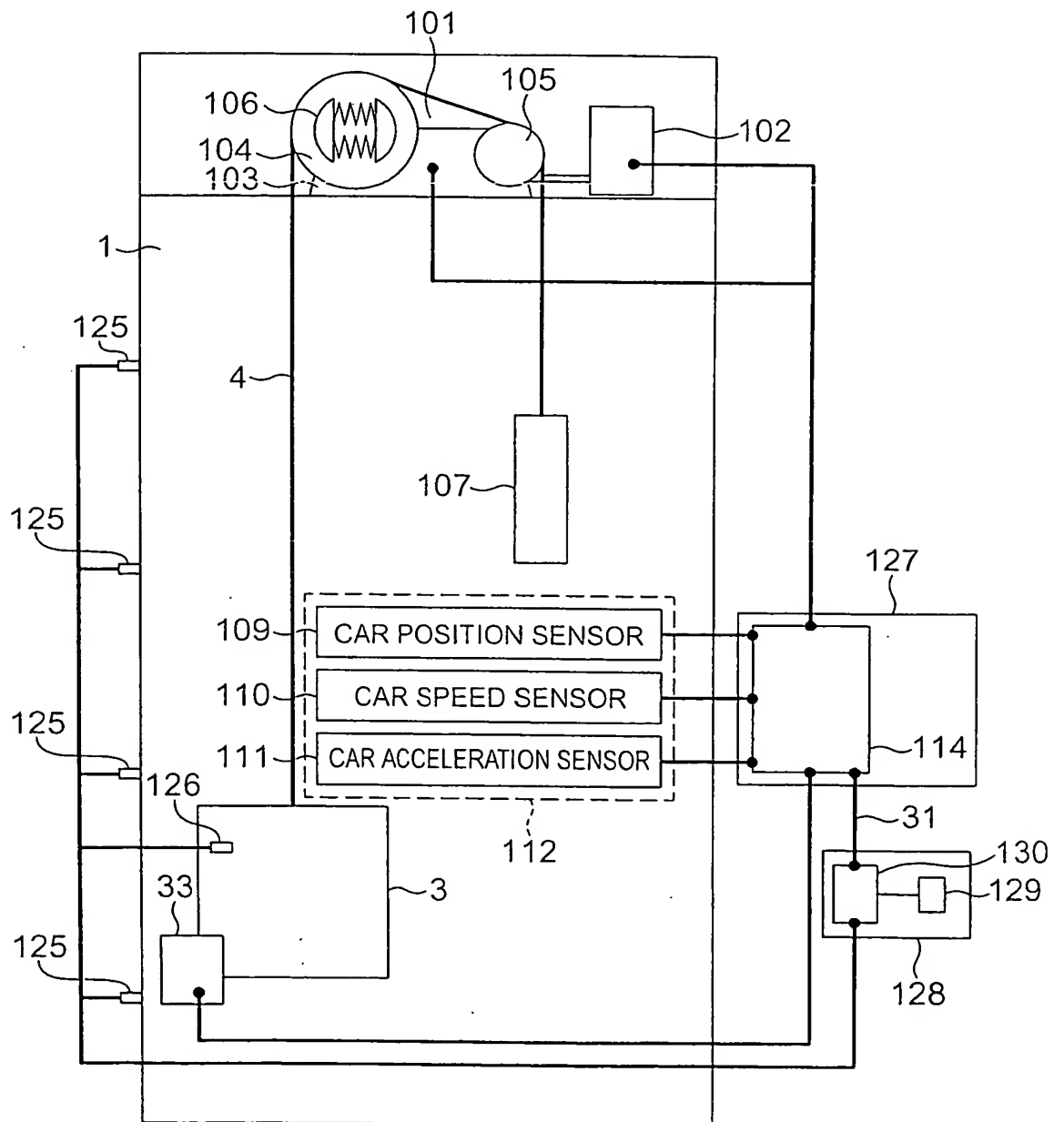


FIG. 21

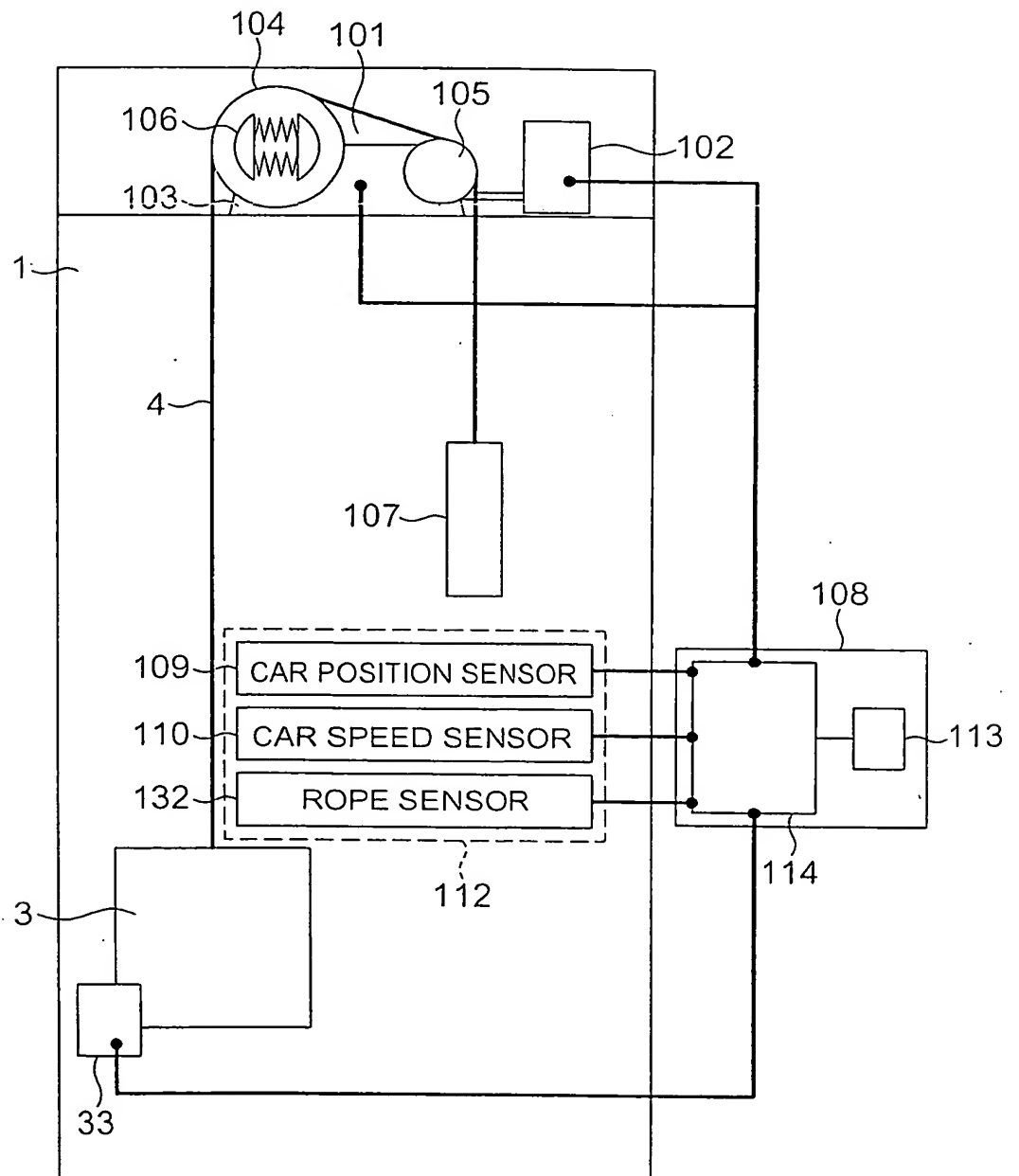
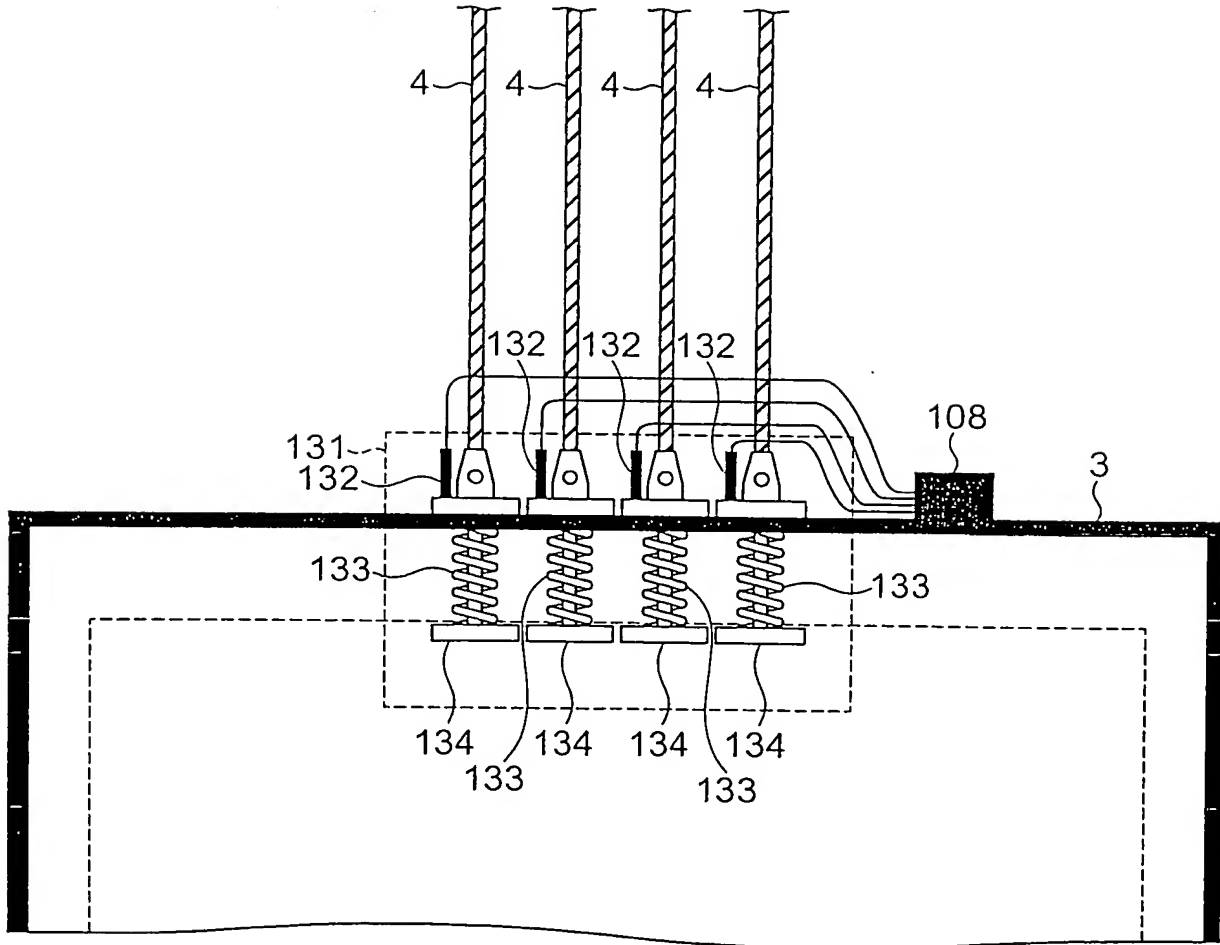


FIG. 22



This diagram illustrates a cross-sectional view of a multi-layered electronic device assembly. The assembly is built upon a substrate 3, which features a top layer 108. Four vertical conductive pillars 4 are mounted on the substrate. Each pillar is connected to a base 131, which is further connected to a spring 133. The springs are connected to a common ground plane 134. The entire assembly is enclosed within a dashed rectangular frame.

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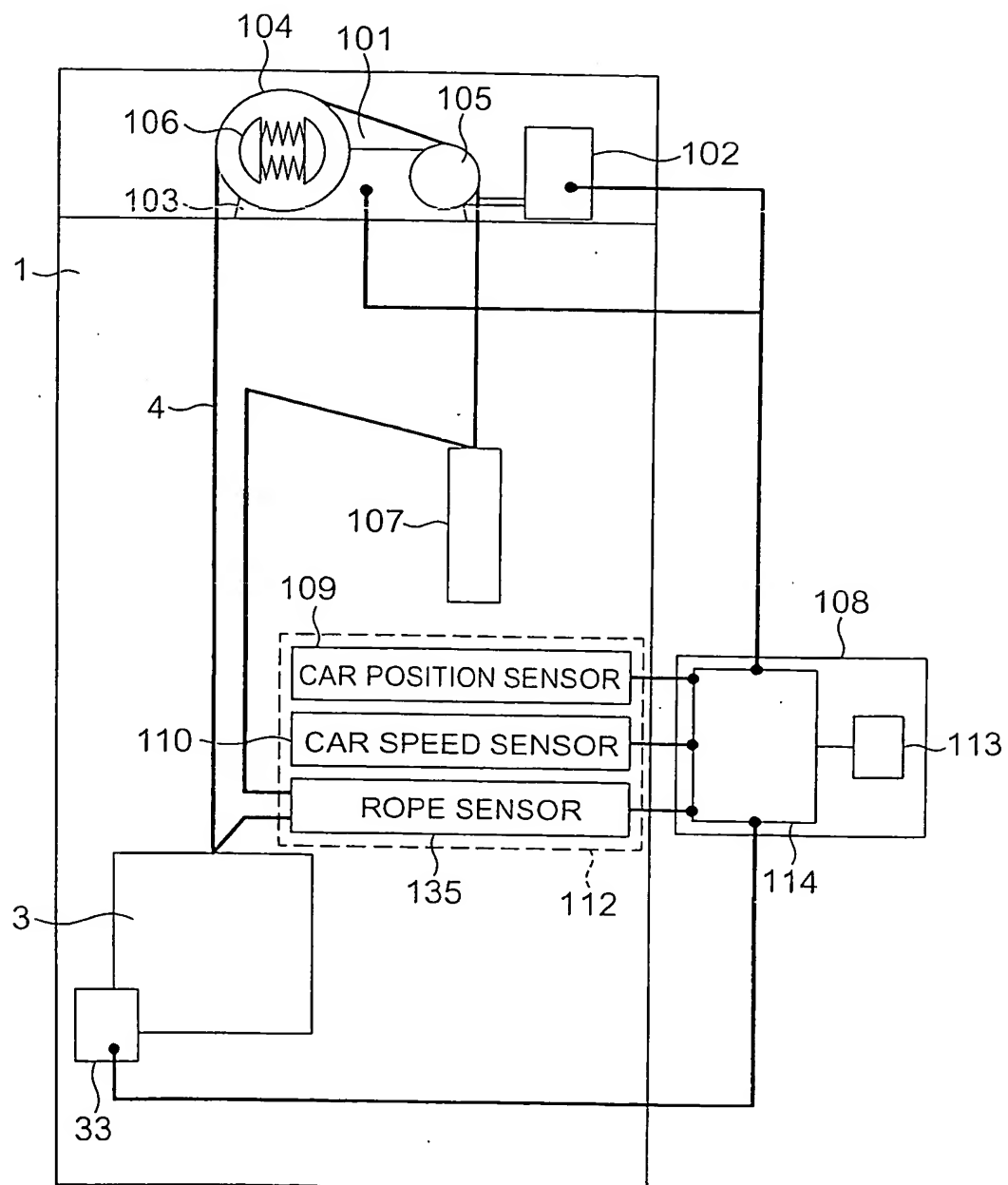


FIG. 25

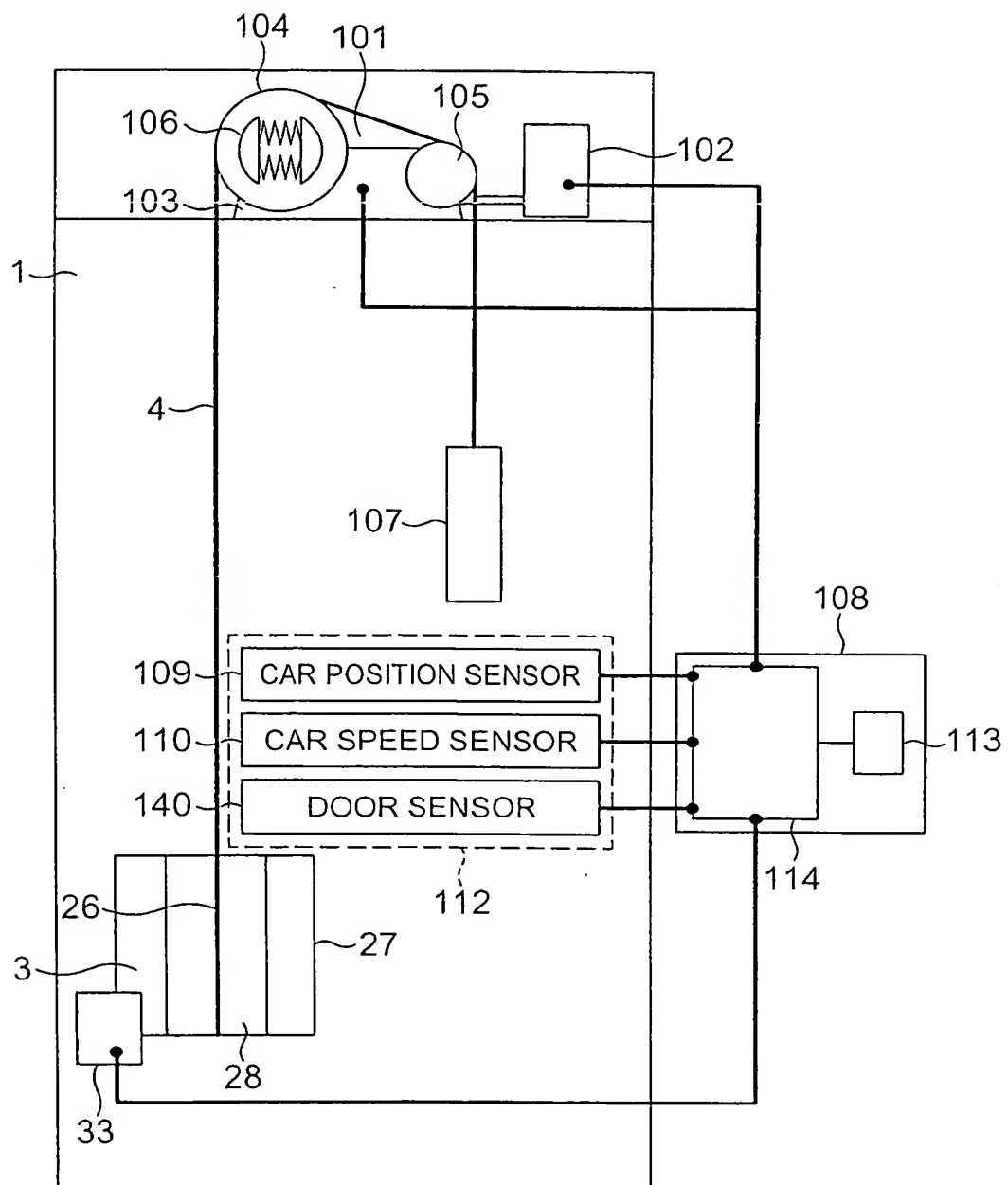


FIG. 26

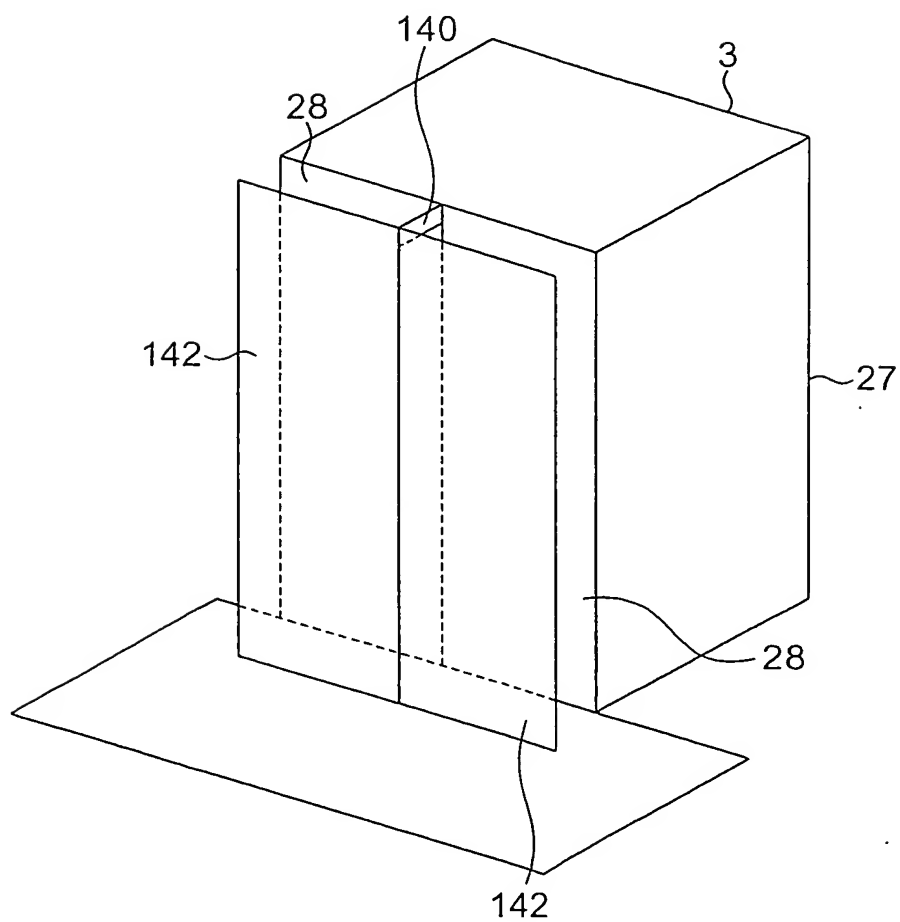


FIG. 27

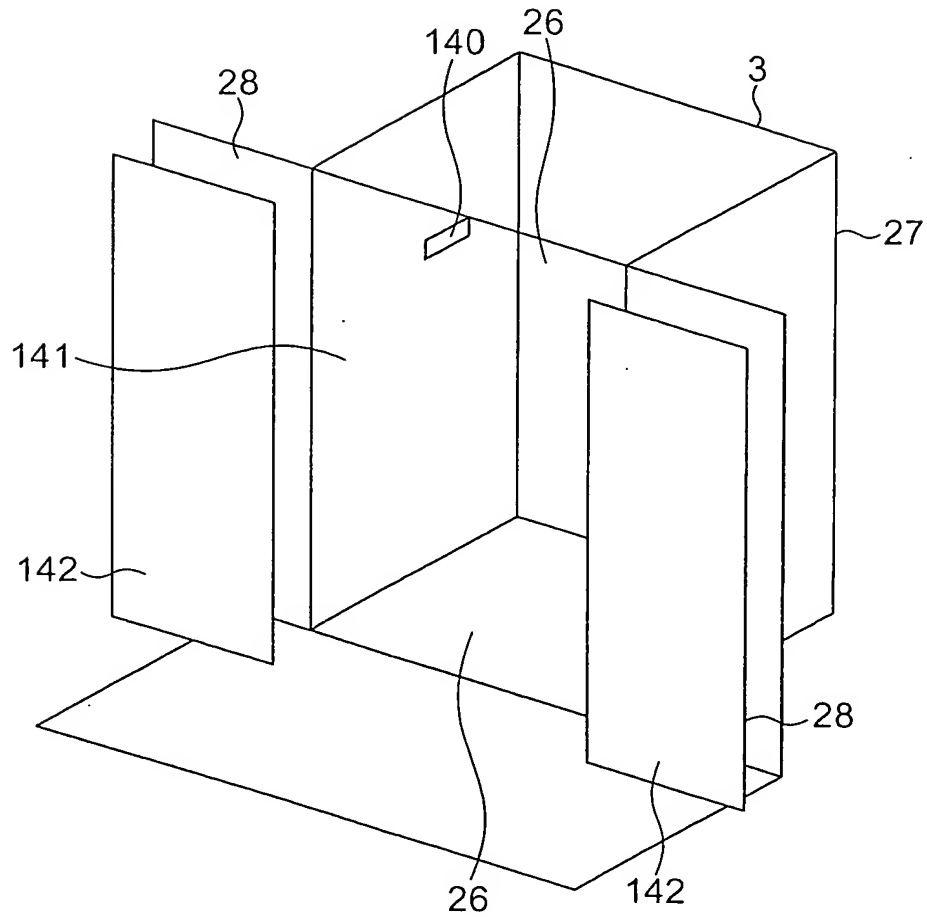


FIG. 28

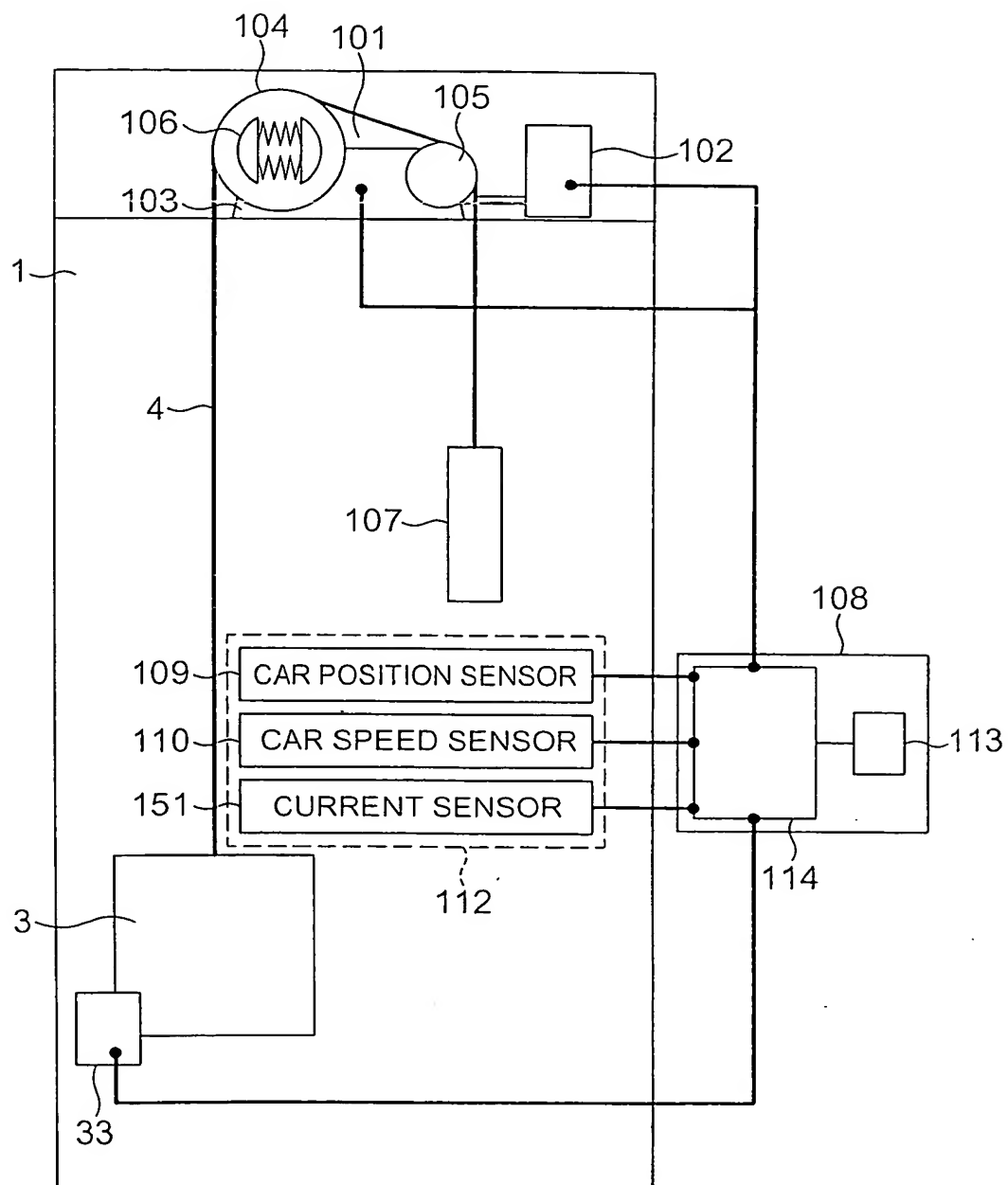


FIG. 29

